

| External_Type | Material_Group | Substances | CAS_Number | Mass | Mass_Percentage_in_Leaf | Massmg |
|----------------|-----------------|--|-----------------|--------------|-------------------------|----------------|
| Wire | Pure metal | Aluminium (Al) | 7429-90-5 | 0.01 | 100.0 | 0.26 |
| | | | Subtotal | 0.01 | 100 | 0.26 |
| Die | Doped silicon | Silicon (Si) | 7440-21-3 | 0.21 | 100.0 | 4.8 |
| | | | Subtotal | 0.21 | 100 | 4.8 |
| Wire | Pure metal | Aluminium (Al) | 7429-90-5 | 0.18 | 100.0 | 4 |
| | | | Subtotal | 0.18 | 100 | 4 |
| Solder Wire | Tin alloy | Tin (Sn) | 7440-31-5 | 0.18 | 90.0 | 4.02 |
| | Tin alloy | Nickel (Ni) - cas no. 7440-02-0 | 7440-02-0 | 0 | 0.5 | 0.02 |
| | Tin alloy | Silver (Ag) | 7440-22-4 | 0 | 2.5 | 0.11 |
| | Tin alloy | Antimony (Sb) | 7440-36-0 | 0.01 | 7.0 | 0.31 |
| | | | Subtotal | 0.19 | 100 | 4.46 |
| Post-plating | Pure metal | Tin (Sn) | 7440-31-5 | 0.66 | 100.0 | 15 |
| | | | Subtotal | 0.66 | 100 | 15 |
| Heat Spreader | Copper alloy | Phosphorous (P) | 7723-14-0 | 0.02 | 0.03 | 0.36 |
| | Copper alloy | Iron (Fe) | 7439-89-6 | 0.06 | 0.11 | 1.34 |
| | Copper alloy | Copper (Cu) | 7440-50-8 | 53.27 | 99.86 | 1213.3 |
| | | | Subtotal | 53.35 | 100 | 1215 |
| Lead Frame | Copper alloy | Phosphorous (P) | 7723-14-0 | 0 | 0.03 | 0.1 |
| | Copper alloy | Iron (Fe) | 7439-89-6 | 0.02 | 0.11 | 0.37 |
| | Copper alloy | Copper (Cu) | 7440-50-8 | 14.55 | 99.84 | 331.47 |
| | Copper alloy | Silver (Ag) | 7440-22-4 | 0 | 0.02 | 0.07 |
| | | | Subtotal | 14.57 | 100 | 332.01 |
| Mould Compound | | Tetrabromobisphenol A/Epichlorohydrin polymer | 40039-93-8 | 0.18 | 0.7 | 4.04 |
| | Polymer | Phenol Formaldehyde resin (generic) | 9003-35-4 | 1.52 | 6.0 | 34.62 |
| | Polymer | Epichlorohydrin/Diethyleneglycol Epoxy resin (generic) | 25928-94-3 | 3.04 | 12.0 | 69.24 |
| | Filler | Silica fused | 60676-86-0 | 17.73 | 70.0 | 403.9 |
| | Carbon Black | Carbon black | 1333-86-4 | 0.08 | 0.3 | 1.73 |
| | Filler | Misc. Silica compounds (generic) | 14808-60-7 | 2.53 | 10.0 | 57.7 |
| | Flame retardant | Antimony Trioxide (Sb2O3) - cas no. 1309-64-4 | 1309-64-4 | 0.25 | 1.0 | 5.77 |
| | | | Subtotal | 25.33 | 100 | 577 |
| Isolator | Copper alloy | Phosphorous (P) | 7723-14-0 | 0 | 0.1 | 0.1 |
| | Copper alloy | Aluminium Trioxide (Al2O3) | 1344-28-1 | 3.82 | 91.6 | 87.02 |
| | Copper alloy | Nickel (Ni) - cas no. 7440-02-0 | 7440-02-0 | 0.04 | 0.9 | 0.85 |
| | Copper alloy | Molybdenum (Mo) | 7439-98-7 | 0.29 | 7.0 | 6.65 |
| | Copper alloy | Manganese (Mn) | 7439-96-5 | 0.02 | 0.4 | 0.38 |
| | | | Subtotal | 4.17 | 100 | 95 |
| Die Attach | Lead alloy | Tin (Sn) | 7440-31-5 | 0.07 | 5.0 | 1.5 |
| | Lead alloy | Silver (Ag) | 7440-22-4 | 0.03 | 2.5 | 0.75 |
| | Lead alloy | Lead (Pb) | 7439-92-1 | 1.22 | 92.5 | 27.75 |
| | | | Subtotal | 1.32 | 100 | 30 |
| | | | Total | 99.99 | 100 | 2277.53 |

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